

IN THE CLAIMS

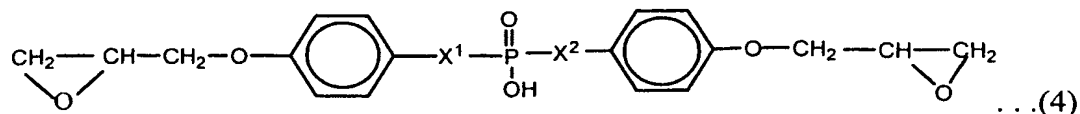
Please amend the claims as follows:

Claims 1-8 (Canceled).

Claim 9 (Currently Amended): A multilayered printed circuit board comprising:  
a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and  
a solder resist layer formed as an outermost layer,  
wherein said solder resist layer contains an elastomer component provided within and at least one resin selected from the group consisting of a thermoplastic resin and a thermosetting resin, and said elastomer component is separated in micro-phase so as to form an island-in-sea structure after curing in said solder resist layer.

Claims 10-31 (Canceled)

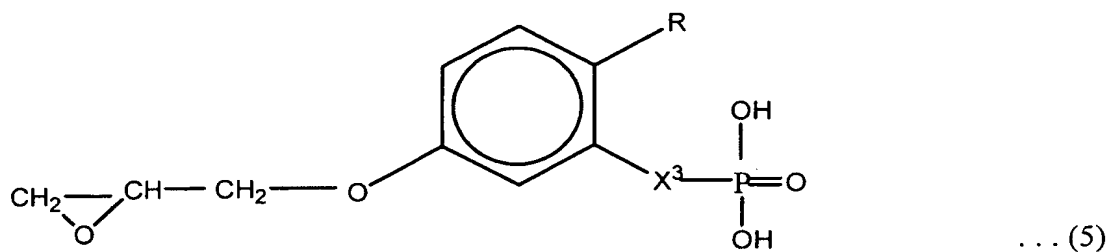
Claim 32 (Previously Presented): A multilayered printed circuit board comprising:  
a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and  
a solder resist layer formed as an outermost layer,  
wherein said solder resist layer contains a P atom-containing epoxy resin, said P atom-containing epoxy resin has bivalent phosphoric acid residue, and has epoxy groups in both terminals of the P atom-containing epoxy resin, and said epoxy resin has the following general formula (4)



wherein  $X^1$  and  $X^2$  respectively represent O or a single bond.

Claim 33 (canceled)

Claim 34 (Previously Presented): A multilayered printed circuit board comprising:  
a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and  
a solder resist layer formed as an outermost layer,  
wherein said solder resist layer contains a P atom-containing epoxy resin, said P atom-containing epoxy resin is an epoxy resin having a monovalent phosphoric acid residue in one terminal of the P atom-containing epoxy resin and an epoxy group in the other terminal of the P atom-containing epoxy resin, and said epoxy resin has the following general formula (5):



wherein  $X^3$  represents O or a single bond; and R represents an alkyl of 2 to 8 carbons.

Claim 35 (Canceled).

Claim 36 (Currently Amended): A multilayered printed circuit board comprising:  
a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and

a solder resist layer formed as an outermost layer,

wherein said solder resist layer contains an elastomer component provided within ~~and~~ at least one resin selected from the group consisting of a thermoplastic resin and a thermosetting resin, said elastomer component is at least one member selected from the group consisting of natural rubber, synthetic rubber, a thermoplastic resin and a thermosetting resin, and said elastomer component is separated in micro-phase so as to form an island-in-sea structure after curing in said solder resist layer.

Claims 37-38 (Canceled).

Claim 39 (Previously Presented): The multilayered printed circuit board according to claim 32,

wherein said solder resist layer contains at least one member selected from the group consisting of a silicon compound, an aluminum compound and a magnesium compound.

Claim 40 (Previously Presented): The multilayered printed circuit board according to claim 34,

wherein said solder resist layer contains at least one member selected from the group consisting of a silicon compound, an aluminum compound and a magnesium compound.